

Appl. No. 10/727,740  
Reply to Office action of 01/05/2005

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claims 1-17 (Canceled).

18. (Currently amended) A fabrication method, comprising the steps of:  
varying the history of wafers within a lot by transporting individual ~~ones~~ wafers thereof  
within a processing tool with multiple processing chambers,  
among said chambers and wafer cassette and/or staging locations  
in various different sequences.
19. (Original) The method of Claim 18, further comprising the contemporaneous step of  
recording process sequence data for said wafers.
20. (Original) The method of Claim 18, further comprising the subsequent step of  
correlating fault and/or parametric data with process sequence data resulting from  
said varying step.
21. (Original) The method of Claim 18, further comprising the subsequent step of  
correlating fault and/or parametric data with process sequence data resulting from  
said varying step, and controlling process parameters accordingly.
- 22-26. (Cancelled).
27. (new) The method of claim 18, wherein said chambers are randomly selected during  
said varying step.